

March 1999 Revised June 2005

# 74LVT162244 • 74LVTH162244 Low Voltage 16-Bit Buffer/Line Driver with 3-STATE Outputs and 25Ω Series Resistors in the Outputs

#### **General Description**

The LVT162244 and LVTH162244 contain sixteen non-inverting buffers with 3-STATE outputs designed to be employed as a memory and address driver, clock driver, or bus oriented transmitter/receiver. The device is nibble controlled. Individual 3-STATE control inputs can be shorted together for 8-bit or 16-bit operation.

The LVT162244 and LVTH162244 are designed with equivalent  $25\Omega$  series resistance in both the HIGH and LOW states of the output. This design reduces line noise in applications such as memory address drivers, clock drivers, and bus transceivers/transmitters.

The LVTH162244 data inputs include bushold, eliminating the need for external pull-up resistors to hold unused inputs.

These buffers and line drivers are designed for low-voltage (3.3V)  $V_{CC}$  applications, but with the capability to provide a TTL interface to a 5V environment. The LVT162244 and LVTH162244 are fabricated with an advanced BiCMOS technology to achieve high speed operation similar to 5V ABT while maintaining a low power dissipation.

#### **Features**

- $\blacksquare$  Input and output interface capability to systems at 5V  $V_{CC}$
- Bushold data inputs eliminate the need for external pullup resistors to hold unused inputs (74LVTH162244), also available without bushold feature (74LVT162244).
- Live insertion/extraction permitted
- Power Up/Power Down high impedance provides glitchfree bus loading
- $\blacksquare$  Outputs include equivalent series resistance of  $25\Omega$  to make external termination resistors unnecessary and reduce overshoot and undershoot
- Functionally compatible with the 74 series 162244
- Latch-up performance exceeds 500 mA
- ESD performance:

Human-body model > 2000V

Machine model > 200V

Charged-device > 1000V

Also packaged in plastic Fine-Pitch Ball Grid Array (FBGA)

#### **Ordering Code:**

Order Number	Package Number	Package Description				
74LVT162244G (Note 1)(Note 2)	BGA54A	54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide				
74LVT162244MEA (Note 2)	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide				
74LVT162244MTD (Note 2)	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm \				
74LVTH162244G (Note 1)(Note 2)	BGA54A	54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide				
74LVTH162244MEA	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide [Tube]				
74LVTH162244MEX	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide [Tape and Reel]				
74LVTH162244MTD	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide [Tube]				
74LVTH162244MTX	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide [Tape and Reel]				

Note 1: Ordering code "G" indicates Trays

Note 2: Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

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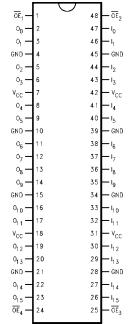
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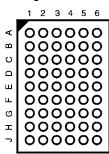
# **Logic Symbol** OE<sub>3</sub> O-

# **Connection Diagrams**

Pin Assignment for SSOP and TSSOP



Pin Assignment for FBGA



(Top Thru View)

### **Pin Descriptions**

Pin Names	Description
<del>OE</del> n	Output Enable Inputs (Active LOW)
I <sub>0</sub> -I <sub>15</sub>	Inputs
I <sub>0</sub> -I <sub>15</sub> O <sub>0</sub> -O <sub>15</sub>	Outputs
NC	No Connect

#### **FBGA Pin Assignments**

	1	2	3	4	5	6
Α	O <sub>0</sub>	NC	OE <sub>1</sub>	OE <sub>2</sub>	NC	$I_0$
В	02	O <sub>1</sub>	NC	NC	I <sub>1</sub>	l <sub>2</sub>
С	O <sub>4</sub>	O <sub>3</sub>	V <sub>CC</sub>	V <sub>CC</sub>	I <sub>3</sub>	I <sub>4</sub>
D	O <sub>6</sub>	O <sub>5</sub>	GND	GND	l <sub>5</sub>	I <sub>6</sub>
E	Ο <sub>8</sub>	07	GND	GND	I <sub>7</sub>	I <sub>8</sub>
F	O <sub>10</sub>	O <sub>9</sub>	GND	GND	l <sub>9</sub>	I <sub>10</sub>
G	O <sub>12</sub>	O <sub>11</sub>	V <sub>CC</sub>	V <sub>CC</sub>	I <sub>11</sub>	I <sub>12</sub>
Н	O <sub>14</sub>	O <sub>13</sub>	NC	NC	I <sub>13</sub>	I <sub>14</sub>
J	O <sub>15</sub>	NC	OE <sub>4</sub>	OE <sub>3</sub>	NC	I <sub>15</sub>

#### **Truth Table**

I	nputs	Outputs
OE <sub>1</sub>	I <sub>0</sub> -I <sub>3</sub>	O <sub>0</sub> -O <sub>3</sub>
L	L	L
L	Н	Н
Н	X	Z
OE <sub>2</sub>	I <sub>4</sub> —I <sub>7</sub>	O <sub>4</sub> -O <sub>7</sub>
L	L	L
L	Н	Н
Н	X	Z
OE <sub>3</sub>	I <sub>8</sub> -I <sub>11</sub>	O <sub>8</sub> -O <sub>11</sub>
L	L	L
L	Н	Н
Н	X	Z
OE <sub>4</sub>	I <sub>12</sub> –I <sub>15</sub>	O <sub>12</sub> -O <sub>15</sub>
L	L	L
L	Н	Н
Н	X	Z

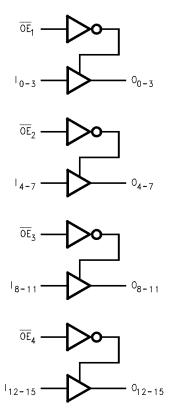
H = HIGH Voltage Level

L = LOW Voltage Level Z = High Impedance

# **Functional Description**

The LVT162244 and LVTH162244 contain sixteen non-inverting buffers with 3-STATE outputs. The device is nibble (4 bits) controlled with each nibble functioning identically, but independent of the other. The control pins can be shorted together to obtain full 16-bit operation.

# **Logic Diagram**



#### **Absolute Maximum Ratings**(Note 3) Parameter Symbol Value Conditions Units -0.5 to +4.6 Supply Voltage $V_{CC}$ VI DC Input Voltage ٧ -0.5 to +7.0 Vo Output Voltage -0.5 to +7.0 Output in 3-STATE ٧ Output in HIGH or LOW State (Note 4) -0.5 to +7.0 DC Input Diode Current -50 $V_I < GND$ mΑ $V_O < GND$ DC Output Diode Current -50 mΑ DC Output Current 64 V<sub>O</sub> > V<sub>CC</sub> Output at HIGH State mΑ 128 $V_O > V_{CC}$ Output at LOW State DC Supply Current per Supply Pin $I_{CC}$ ±64 mΑ DC Ground Current per Ground Pin ±128 $I_{GND}$ Storage Temperature -65 to +150 ۰С $T_{STG}$

#### **Recommended Operating Conditions**

Symbol	Parameter	Min	Max	Units
V <sub>CC</sub>	Supply Voltage	2.7	3.6	V
VI	Input Voltage	0	5.5	V
I <sub>OH</sub>	HIGH-Level Output Current		-12	mA
I <sub>OL</sub>	LOW-Level Output Current		12	mA
T <sub>A</sub>	Free Air Operating Temperature	-40	+85	°C
$\Delta t/\Delta V$	Input Edge Rate, V <sub>IN</sub> = 0.8V–2.0V, V <sub>CC</sub> = 3.0V	0	10	ns/V

Note 3: Absolute Maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum rated conditions is not implied.

Note 4: Io Absolute Maximum Rating must be observed.

#### **DC Electrical Characteristics**

Symbol	l Parameter		V <sub>CC</sub>	T <sub>A</sub> = -40°C	to +85°C	Units	Conditions	
Symbol	Paramete	Farameter		Min	Max	Units		
V <sub>IK</sub>	Input Clamp Diode Voltage		2.7		-1.2	V	I <sub>I</sub> = -18 mA	
V <sub>IH</sub>	Input HIGH Voltage		2.7-3.6	2.0		V	$V_0 \le 0.1V$ or	
V <sub>IL</sub>	Input LOW Voltage		2.7-3.6		0.8	V	$V_O \ge V_{CC} - 0.1V$	
V <sub>OH</sub>	Output HIGH Voltage		2.7-3.6	V <sub>CC</sub> -0.2		V	I <sub>OH</sub> = -100 μA	
			3.0	2.0		v	I <sub>OH</sub> = -12 mA	
V <sub>OL</sub>	Output LOW Voltage		2.7		0.2	V	$I_{OL} = 100  \mu A$	
			3.0		0.8	v	I <sub>OL</sub> = 12 mA	
I <sub>I(HOLD)</sub>	Bushold Input Minimum Drive		3.0	75		μА	$V_I = 0.8V$	
(Note 5)			3.0	-75		μА	$V_I = 2.0V$	
I <sub>I(OD)</sub>	Bushold Input Over-Drive		3.0	500		μА	(Note 6)	
(Note 5)	Current to Change State		5.0	-500		μΑ	(Note 7)	
l <sub>l</sub>	Input Current		3.6		10		$V_{I} = 5.5V$	
		Control Pins	3.6		±1	μА	V <sub>I</sub> = 0V or V <sub>CC</sub>	
		Data Pins	3.6		-5	μΛ	$V_I = 0V$	
		Data i ilis	3.0		1		$V_I = V_{CC}$	
OFF	Power Off Leakage Current		0		±100	μΑ	$0V \le V_I \text{ or } V_O \le 5.5V$	
I <sub>PU/PD</sub>	Power Up/Down		0-1.5V		±100	μА	V <sub>O</sub> = 0.5V to 3.0V	
	3-STATE Current		0-1.50		±100	μΛ	$V_I = GND \text{ or } V_{CC}$	
l <sub>OZL</sub>	3-STATE Output Leakage Cur	rent	3.6		-5	μΑ	V <sub>O</sub> = 0.5V	
I <sub>OZH</sub>	3-STATE Output Leakage Cur	rent	3.6		5	μΑ	V <sub>O</sub> = 3.0V	
I <sub>OZH</sub> +	3-STATE Output Leakage Current		3.6		10	μΑ	$V_{CC} < V_O \le 5.5V$	
Іссн	Power Supply Current Power Supply Current		3.6		0.19	mA	Outputs HIGH	
I <sub>CCL</sub>			3.6		5	mA	Outputs LOW	
I <sub>CCZ</sub>	Power Supply Current		3.6		0.19	mA	Outputs Disabled	

# DC Electrical Characteristics (Continued)

Symbol	Parameter	V <sub>CC</sub> T <sub>A</sub> = -40°C to +85°C		Units	Conditions	
Cymbol	T diameter	(V)	Min	Max	Omis	Conditions
I <sub>CCZ</sub> +	Power Supply Current	3.6		0.19	mA	$V_{CC} \le V_O \le 5.5V$ ,
		0.0		0.10		Outputs Disabled
Δl <sub>CC</sub>	Increase in Power Supply Current	3.6		0.2	mA	One Input at V <sub>CC</sub> - 0.6V
	(Note 8)	3.0		0.2	IIIA	Other Inputs at V <sub>CC</sub> or GND

Note 5: Applies to bushold versions only (74LVTH162244).

Note 6: An external driver must source at least the specified current to switch from LOW-to-HIGH.

Note 7: An external driver must sink at least the specified current to switch from HIGH-to-LOW.

Note 8: This is the increase in supply current for each input that is at the specified voltage level rather than V<sub>CC</sub> or GND.

### **Dynamic Switching Characteristics** (Note 9)

Symbol	Parameter	v <sub>cc</sub>	$T_A = 25^{\circ}C$		Units	Conditions	
Cymbol	i arameter	(V)	Min	Тур	Max	Omis	$\textbf{C}_{\textbf{L}}=\textbf{50}$ pF, $\textbf{R}_{\textbf{L}}=\textbf{500}\Omega$
V <sub>OLP</sub>	Quiet Output Maximum Dynamic V <sub>OL</sub>	3.3		0.8		V	(Note 10)
V <sub>OLV</sub>	Quiet Output Minimum Dynamic VOL	3.3		-0.8		V	(Note 10)

Note 9: Characterized in SSOP package. Guaranteed parameter, but not tested.

Note 10: Max number of outputs defined as (n). n-1 data inputs are driven 0V to 3V. Output under test held LOW.

#### **AC Electrical Characteristics**

		T <sub>A</sub> = -				
Symbol	Parameter	V <sub>CC</sub> = 3.3	3V ± 0.3V	V <sub>CC</sub> =	Units	
Symbol		Min	Max	Min	Max	Units
t <sub>PLH</sub>	Propagation Delay Data to Output	1.4	4.0	1.4	4.8	ns
t <sub>PHL</sub>		1.2	3.7	1.2	4.1	110
t <sub>PZH</sub>	Output Enable Time	1.2	5.1	1.2	6.5	ns
t <sub>PZL</sub>		1.4	5.4	1.4	6.9	115
t <sub>PHZ</sub>	Output Disable Time	2.0	5.0	2.0	5.4	ns
t <sub>PLZ</sub>		1.5	5.0	1.5	5.4	115
t <sub>OSHL</sub>	Output to Output Skew		1.0		1.0	ns
t <sub>OSLH</sub>	(Note 11)		1.0		1.0	115

Note 11: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (toSHL) or LOW-to-HIGH (toSLH).

#### Capacitance (Note 12)

Symbol Parameter		Conditions	Typical	Units	
C <sub>IN</sub>	Input Capacitance	$V_{CC} = 0V$ , $V_I = 0V$ or $V_{CC}$	4	pF	
C <sub>OUT</sub>	Output Capacitance	$V_{CC} = 3.0V$ , $V_{O} = 0V$ or $V_{CC}$	8	pF	

Note 12: Capacitance is measured at frequency f = 1 MHz, per MIL-STD-883, Method 3012.

#### Physical Dimensions inches (millimeters) unless otherwise noted ○ 0.10 B В 5.5 8.0 Α (0.8)0.4 0.10 A -(0.75) 000000 ABCDEFGHJ PIN ONE 8 0.8 1/23<sup>j</sup>456 Top **Bottom** 54X 0.5<sup>+0.05</sup> View View 0.15(M) C A B 0.08(M) C // 0.15 C SEATING PLANE

#### NOTES:

1.4MAX

A. THIS PACKAGE CONFORMS TO JEDEC M0-205

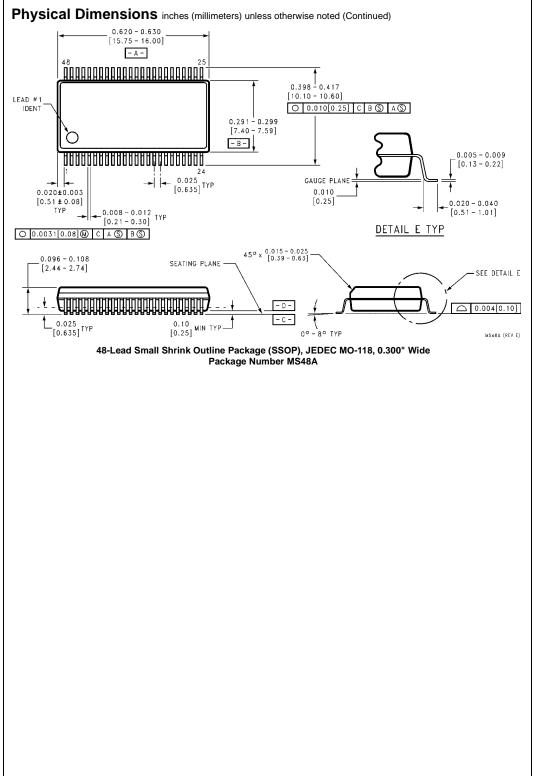
0.45 0.35

- **B. ALL DIMENSIONS IN MILLIMETERS**
- C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)
  .35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS
  D. DRAWING CONFORMS TO ASME Y14.5M-1994

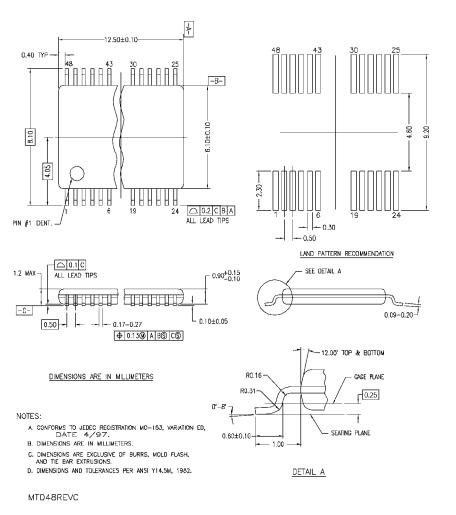
○ 0.10 C

#### BGA54ArevD

54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide Package Number BGA54A



# Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

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